Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP Adv Svcs zl Mod w/Win Svr 2008 R2 Std / J9666A
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Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Screw Drivers	T-6, T-8, T-10, Box type
Phillips Screw Driver	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the CF card on the PCA. Refer to Pic.1 (a)
2. Using the Phillips screw driver, removes the 4 Phillips screw attaching the hard drive to the PCA. Refer to Pic.1 (b)
3. Remove the 4 screws that attached the brackets to the hard drive using a T-8 screwdriver. Refer to Pic.2 (c)
4. Remove the plunger that attached the Com-E module into the PCA using a T-10 screwdriver. Refer to Pic.3 (d)
5. Remove the 4 standoffs that attached the Com-E module onto the PCA using the Boxtype Torx screwdriver. Refer to Pic.3 (e)
6. Remove another 1 standoff, using the Boxtype Torx screwdriver. Refer to Pic.3 (f)
7. Remove the Com-E module.
8. Remove the bulkhead by removing the 5 screws securing the bulkhead onto the PCA. Remove 3 screws using the T-6 screwdriver [Pic.4 (g)] and another 2 screws using the T-10 screwdriver [Pic.4 (h)]
9. Remove two screws and springs on the bulkhead. Refer to Pic.5 (i)
10. Remove the 4 screws that attached the heatsink onto the PCA using the T-10 Torx screwdriver. Refer to Pic.6 (j)
11. Remove the guide pin by using a T-10 Torx screwdriver to remove the 1 screw that attached the guide pin to the PCA. Refer to Pic.6 (k)
12. Remove the 3 standoffs via bottom 3 screws using the T-10 screwdriver. Refer to Pic.6 (m)
13. Remove the 5 standoffs via bottom 5 screws using the T-8 screwdriver. Refer to Pic.7 (n)
14. Remove the solder-anchor heatsink (towards right of PCA when looking from front) by releasing the catch from the 2 anchors. Refer to Pic.8 (o)
15.
16.
17.
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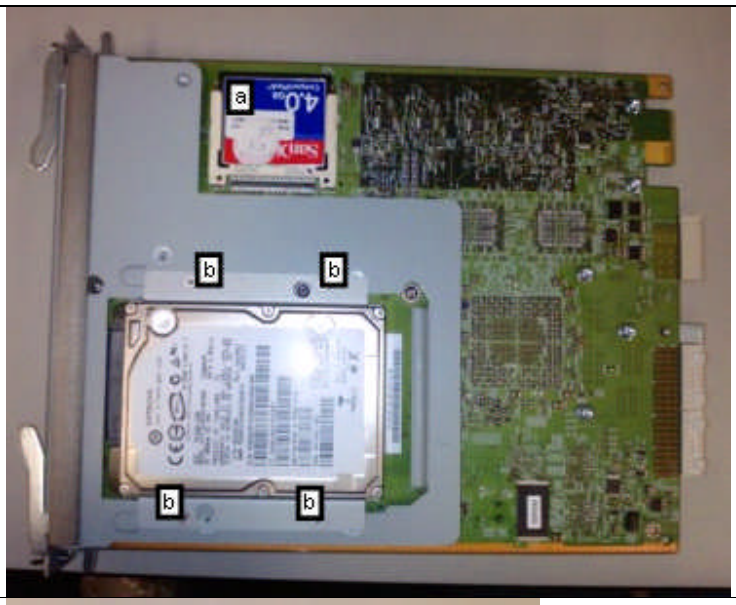
19.
20.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Pic	Illustration

1	
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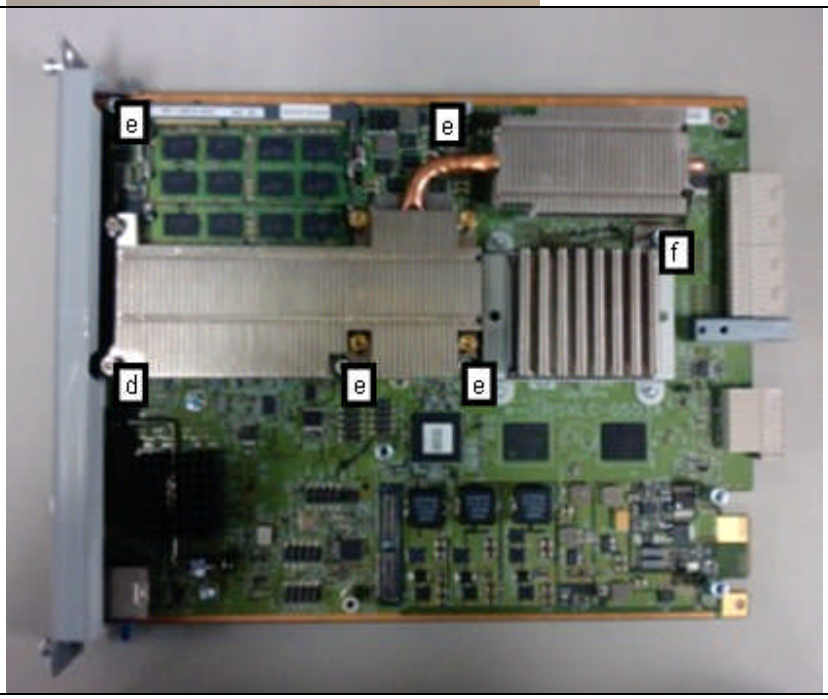
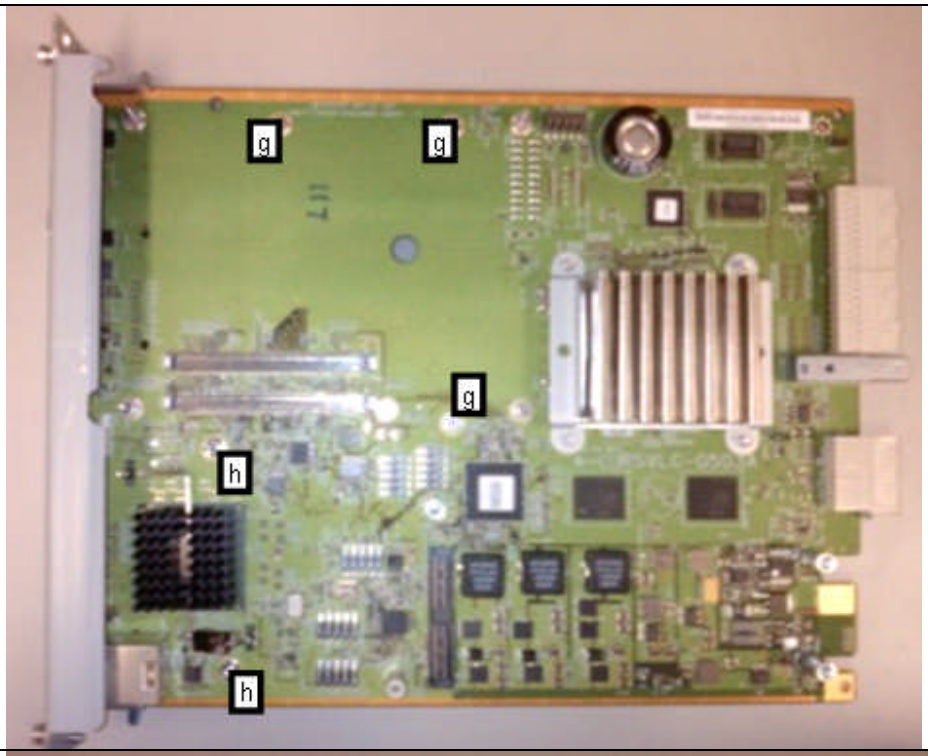
3	

4		
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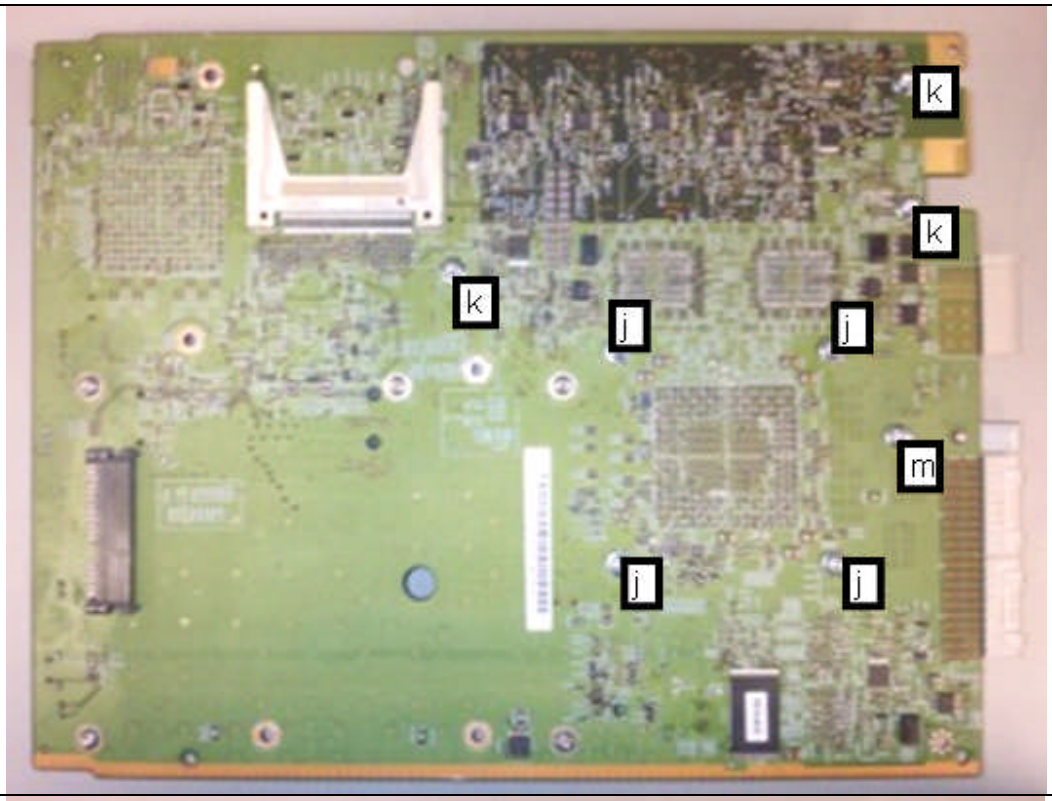
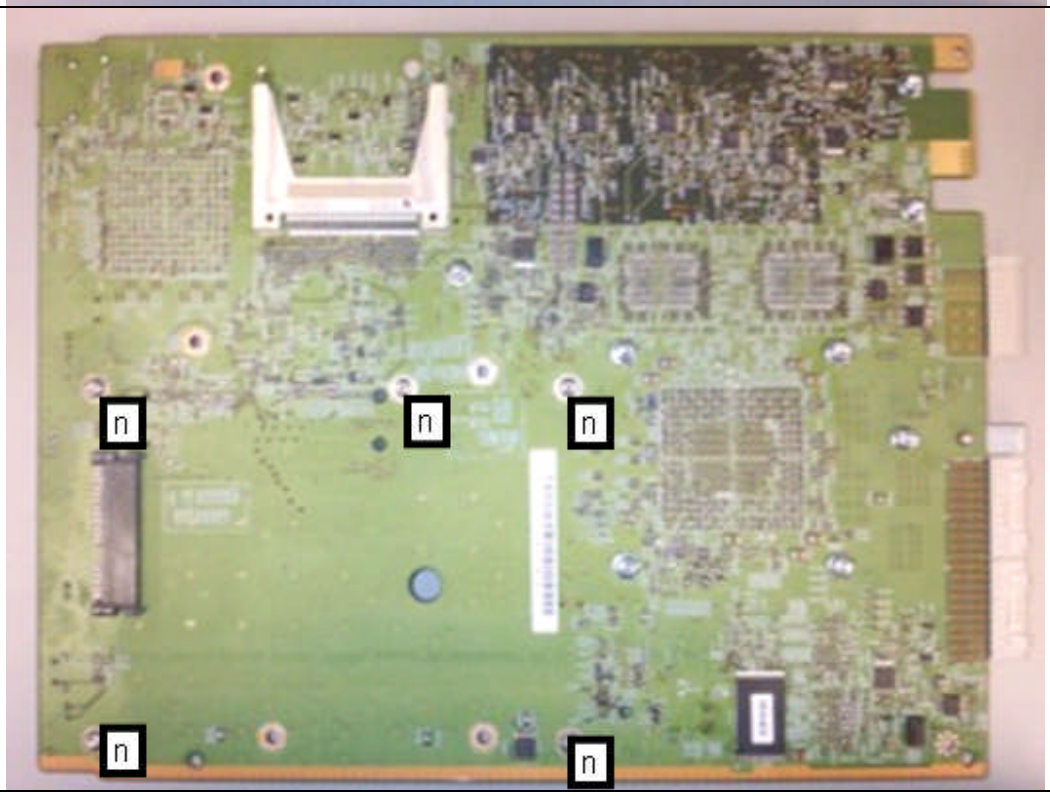
6	
7	

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